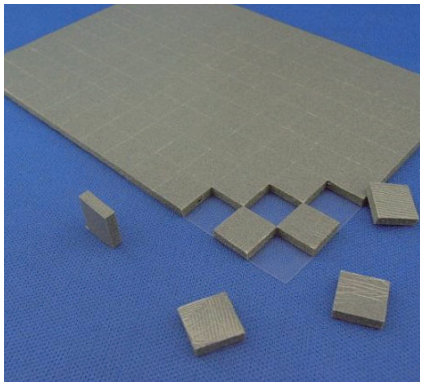
Thermally conductive Silicone-free type

COOLPROVIDE™ / CPSS

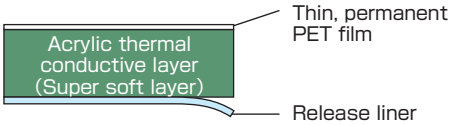


Super low hardness (ASKER C 8) Thermal Pad

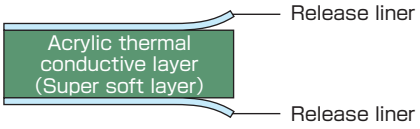
Features

- 2W/m·K and compilable (ASKER C 8) allows for less pressure on the heatsource, such as the IC or PCB.
- Allows for lower thermal resistance on an uneven surfaces.
- Silicone-free generates no siloxane gas and oil bleeding.

One-side tacky type／CPSS-F



Both-side tacky type／CPSS



(The values are measured values, but not the product specifications or guaranteed.)

Test type	Unit	Standard	CPSS-F	CPSS
Thermal Conductivity	W/m·K	JIS R 2616 (Hot-wire method)	2.0	2.0
		ISO22007-2 (Hot Disc method)	1.4	1.4
Color	—	—	Darkgreen	Darkgreen
Thickness	mm	—	1.0／1.5／2.0 2.5／3.0／4.0	3.0／4.0
Specific Gravity	—	JIS Z 8807	1.92	1.92
Hardness*1	ASKER C	JIS K 7312	8	8
	Shore 00	ASTM D 2240	33	33
Tensile strength	MPa	JIS K 6251	0.28	—
Elongation rate	%	JIS K 6251	8.9	—
Volume Resistivity	Ω·cm	JIS K 6911 compliant	1.0×10^{12}	1.0×10^{12}
Breakdown voltage	kV/mm	JIS C 2110-1 compliant	3.5	—
Withstanding voltage	kV/mm	JIS C 2110-1 compliant	2.8	—
Tracking resistance	—	JIS C 2134	PLC:0 (600V or higher) (t=3.0mm)	PLC:0 (600V or higher) (t=3.0mm)
Dielectric constant 1MHz	—	Company standard	14.6	—
Loss tangent 1MHz	—	Company standard	0.09	—
Flammability	—	UL94	V-2(t1.0 - 3.0mm) V-0(t4.0mm)	—
Operating temp	℃	—	-40～100	-40～100
Available max. dimension*2	mm	—	200×500	200×500

＊1) Measured Ultra soft/Super soft/Soft layer, minimum 10mm stacked.
＊2) For usable dimensions, custom cuts, and material yield, contact your local sales department.